INVERTIBLE MICROFEATURE DEVICE PACKAGES AND ASSOCIATED METHODS

ABSTRACT OF THE DISCLOSURE

Invertible microfeature device packages and associated methods for manufacture and use are disclosed. A package in accordance with one embodiment includes a microfeature device having a plurality of device contacts, and a conductive structure electrically connected to the contacts. The conductive structure can have first and second package contacts accessible for electrical coupling to at least one device external to the package, with the first package contacts accessible from a first direction and the second package contacts configured to receive solder balls and accessible from a second direction opposite the first. An encapsulant can be disposed adjacent to the microfeature device and the conductive structure and can have apertures aligned with the second package contacts to contain solder balls carried by the second package contacts. Accordingly, the package can be connected in either a face-up or face-down orientation, and/or can be connected to another, similar device in either a face-to-face arrangement or a back-to-back arrangement.

FIGURE 2